Grinding protection of backside of wafer

Back grinding tape

Feature
The back grind tape is used for back surface grinding (back grinding) of the wafer. It is used to protect against contamination such as scratches caused by external foreign matter, chipping / cracking (cracking) and contamination.

- Excellent adhesion to uneven wafer such as circuit surface
- Excellent easy peelability

Use
Grinding and cleaning process of semiconductor wafer

Construction

<table>
<thead>
<tr>
<th>Layer</th>
<th>Thickness</th>
</tr>
</thead>
<tbody>
<tr>
<td>Adhesive layer</td>
<td>0.08mm</td>
</tr>
<tr>
<td>Substrate (PET)</td>
<td>0.025mm</td>
</tr>
<tr>
<td>Adhesive layer</td>
<td>0.03mm</td>
</tr>
</tbody>
</table>

Characteristic specification

- Base material: Polyester resin

Characteristic

<table>
<thead>
<tr>
<th>Item name</th>
<th>Part number</th>
<th>Thickness (mm)</th>
<th>Adhesive force</th>
</tr>
</thead>
<tbody>
<tr>
<td>Back grinding tape</td>
<td>214D</td>
<td>0.115</td>
<td>25</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td>15</td>
</tr>
</tbody>
</table>

Strong adhesive surface (N/25mm)
Weak adhesive surface (N/25mm)

* PET # 25 backed adherend: stainless steel
After pasting, leave for 24 hours
Tensile speed 300 mm / min 180 degrees peel

Precautions on use

- All technical data are prepared based on tests and measured values conducted at the laboratory of Joint Giken Kagaku Co., Ltd. However, product characteristics may vary greatly depending on environment and adherend. Therefore, regarding these characteristic data, it is a reference value, not a guaranteed value.
- Before using it please make sure that this product is suitable for the intended use and environment.
- The above measurement is data at room temperature (23 ° C).
- In case of low temperature (5 °C or less), adhesion may decrease sharply.

Caution on storage

- Please be sure to put it in a box and keep it.
- Please choose a cold and dark place not to be exposed to direct sunlight for the storage location.
In particular, please do not expose to high temperature and high humidity (temperature 30 °C or more and humidity 50% or more forbidden).

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